PCN Number:	2018010200	20180102000 PCN Date: Feb. 12, 2						12, 2018			
Title: .3 720p S245 TRP DMD Process Change and DLPC34xx Controller Software/Firmware Change											
Customer Contact:	DLP-PCN-Te	DLP-PCN-Team@list.ti.com			Dept:	D	DLP CQE				
Proposed 1 st Ship Date:	May 12,2018	5		mated ilability	Sample /:	Fe	eb. 12, 2018				
Change Type:											
Assembly S	Site		Design				Wafer Bump	o Site			
Assembly Process			Data Sheet				Wafer Bump Material				
Assembly Materials			Part number change			\square	Wafer Bump Process				
	Specification			Software /Firmware			Wafer Fab Site				
	ipping/Labeling				Ħ	Wafer Fab Materials					
					Ħ	Wafer Fab Process					
				Detail	6			100000			
Description of	Change		PCNI	Jetan	5						
Description of							atawi waatawia		in the		
Texas Instrume											
DMD process as											
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through an end											
	cess DMDs hav		,	•	, ,						
	ormation can be							anet.			
	quirements for										
	SW is backward					I er	courages cu	stomers	to		
	new SW imme										
 Consult you 	r application en	igineer f	or questior	ns or if y	you need	acc	ess to TI's m	ySecure	e Software		
site.											
Reason for Ch	ange:										
This change is p	· ·			<u>· ·</u>							
Anticipated in	ipact on Form	, Fit, Fi	inction, Q	uality	or Reliab	ility	/ (positive /	/ negat	ive):		
None											
Anticipated in											
🛛 🛛 No Impa	t to the $ \sqcup $						tent reports a				
	Material production data and will be available following the production										
Declarati	Declaration release. Upon production release the revised reports can be										
							e. There is n	•			
		mater	ial meeting	g currer	nt regulate	ory	compliance r	equiren	ents with		
this PCN change.											
Changes to pr	oduct identifi	cation r	esulting f		is PCN:						
Changes to pr	oduct identifi	cation r	esulting f		is PCN:						
	oduct identifi		esulting f Orderable		is PCN: SW		DMD				
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	Orderable	New (Orderable	rom th	SW	:	Samples Available		D MP ble now		
Device	Orderable P/N	New (Drderable P/N	Avail Avail	SW ability** able now	:	Samples Available now				
Device	Orderable P/N	New (Drderable P/N	Avail Avail	SW ability**	:	Samples Available now Available	Availa			
Device .3 720p S245	Orderable P/N 7212-313BK	New (Drderable P/N 2-323BK	Avail Avail	SW ability** able now	¢	Samples Available now	Availa	ble now		
Device .3 720p S245	Orderable P/N 7212-313BK	New C 7212 DLP3	Drderable P/N 2-323BK 010AFQK	Avail Avail	SW ability** able now	<	Samples Available now Available	Availa	ble now		
Device .3 720p S245 .3 720p S245	Orderable P/N 7212-313BK DLP3010FQK	New C 7212 DLP3 Orig	Drderable P/N 2-323BK 010AFQK inal	Avail Avail Avail	SW ability** able now		Samples Available now Available	Availa	ble now		
Device .3 720p S245 .3 720p S245	Orderable P/N 7212-313BK	New O 7212 DLP3 Orig Softw	Drderable P/N 2-323BK 010AFQK inal /are /	Avail Avail Avail Avail	SW ability** able now able now		Samples Available now Available now	Availa Availa	ble now		
Device .3 720p S245 .3 720p S245 C	Orderable P/N 7212-313BK DLP3010FQK	New O 7212 DLP3 Orig Softw Firm	Drderable P/N 2-323BK 010AFQK inal /are /	Avail Avail Avail Avail	SW ability** able now able now v Proces	5	Samples Available now Available now	Availa Availa ity**	ble now		

Qualification Data

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Product Applications:

See the DMD device sheet and Application Note "<u>Software Requirements for TI DLP[®] Pico[™] TRP</u> <u>Digital Micromirror Devices</u>" for application details.

<u>.3 720p S245 TRP Device</u> Part# (7212-323BK, DLP3010AFQK)

Qualification Tests & Results:

The .3 720p S245 TRP Device Qualification has passed. The following life, environmental, and inspection tests were conducted as per the approved qualification plan and test requirements. Details are mentioned below.

Test	Conditions	Quantity	Results	
A. Life Test: *				
High Temp Operating Life	95°C, 500hr or equivalent	40	Pass	
Nominal Operating Life w/o Precondition	70°C, 670hr or equivalent	40	Pass	
Preconditioning + Nominal Operating Life:				
(a) Precondition	UBH 110°C/85%RH, 500hr	40	Pass	
(b) Nominal Operating Life	70°C, 670hr or equivalent			
Low Temp Operating Life	-10°C, 500hr or equivalent	40	Pass	
Projector Life w/o Precondition	Ambient Temperature, 1000hr or equivalent	9	Pass	
Preconditioning + Projector Life				
(a) Precondition	UBH 110°C/85%RH, 500hr	9	Pass	
(b) Projector Life	Ambient Temperature, 500hr or equivalent		rass	
B. Environmental Tests: *				
High Temp Storage Life	125°C, 500hr or equivalent	30	Pass	
Temperature Cycling	0°C/+100°C 1000cycles	77	Pass	
Unbiased HAST	UBH 110°C/85%RH, 500hr	27	Pass	
ESD	RT, HBM per Data Sheet	9	Pass	
Latch Up	RT, +/-100mA	9	Pass	
Mechanical Stress Sequence (a) Electrical Test				
(b) Mechanical Shock	1500g, 0.5ms, 6axis, 5 pulses		Pass	
(c) Vibration	20g, 20-2000Hz, All planes (x, y, z)	32		
(d) Acceleration	10Kg, Y1 plane only			
(e) Electrical Test				
Thermal Stress Sequence				
(a) Electrical Test			Pass	
(b) Thermal Shock	0°C/+100°C, 15 cycles	32		
(c) Temp. Cycle	0°C/+100°C, 100 cycles	52		
(d) Moisture Resistance	10 days			
(a) Electrical Test				
C. Inspection Tests:			-	
Physical Dimensions		10	Pass	
Internal Water Vapor		10	Pass	
Window Pull		10	Pass	
Bond Strength		9	Pass	
D. Others:				
Image Quality		30	Pass	
Optical Performance		30	Pass	

* Any conditions beyond the Recommended Operating Conditions listed in the Datasheet are run at accelerated test conditions.

For questions regarding this notice, emails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com